L Number	Hits	Search Text	DB	Time stamp
1	84	<pre>((mirror adj image) near (pin or pad)) and (chip or die) and (ic or semiconductor)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/23 20:20
2	29	(((mirror adj image) near (pin or pad)) and (chip or die) and (ic or semiconductor)) and (@ad<19990512)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/23 20:21
3	16	<pre>(((mirror adj image) near (pin or pad)) and (chip or die) and (ic or semiconductor)) and ((conventional or standard) with (pin or pad))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/23 21:26
4	10	<pre>((((mirror adj image) near (pin or pad)) and (chip or die) and (ic or semiconductor)) and ((conventional or standard) with (pin or pad))) and (@ad<19990512)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/23 21:26
5	1	("5502621").PN.	USPĀT	2003/07/23 19:44
6	1	5805520.URPN.	USPAT	2003/07/23 20:03
7	4	("4724531" "4994896" "5502621" "5579277").PN.	USPAT	2003/07/23 20:03
8	11	5502621.URPN.	USPAT	2003/07/23 20:06
9	111	<pre>(((mirror adj image) or reverse) near (pin or pad)) and (chip or die) and (ic or semiconductor)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/23 21:25
10	39	((((mirror adj image) or reverse) near (pin or pad)) and (chip or die) and (ic or semiconductor)) and (@ad<19990512)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/23 21:19
11	2	5691570.URPN.	USPAT	2003/07/23
12	107	((((mirror adj image) or reverse) near (pin or pad)) and (chip or die) and (ic or semiconductor)) not 5502621.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/23 21:19
13	27	<pre>((((mirror adj image) or reverse) near (pin or pad)) and (chip or die) and (ic or semiconductor)) not ((mirror adj image) near (pin or pad)) and (chip or die) and (ic or semiconductor))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/23 21:20
14	248	<pre>(((mirror adj image) or reverse) near (pattern)) and (chip or die) and (ic or semiconductor)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/07/23 21:24
15	69	<pre>((((mirror adj image) or reverse) near (pattern)) and (chip or die) and (ic or semiconductor)) and ((conventional or standard) with (pin or pad or pattern))</pre>	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/07/23 21:26
16	36	<pre>(((((mirror adj image) or reverse) near (pattern)) and (chip or die) and (ic or semiconductor)) and ((conventional or standard) with (pin or pad or pattern))) and (@ad<19990512)</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/07/23 21:26